

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	16
Option	Pb-Free

Molding Compound			
Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	1.00 E-03	15738
SiO2 Filler	85	9.48 E-03	148639
Phenol Resin	5	5.58 E-04	8743
Antimony_Sb2O3	0.5	5.58 E-05	874
Brominated Resin	0.5	5.58 E-05	874

Leadframe			
Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.52 E-02	552150
Ni	3	1.10 E-03	17219
Si	0.65	2.38 E-04	3731
Mg	0.15	5.49 E-05	861

Internal Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Ag	100	5.00 E-04	7838

External Leadframe Plating			
Item	% of Plating	Weight (g)	PPM
Sn	100	1.42 E-03	22215

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Au	99.99	3.13 E-04	4909

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	212859

Die Attach			
Item	% of Die Attach	Weight (g)	PPM
Resin	25	5.34 E-05	838
Ag Filler	75	1.60 E-04	2513

Package Totals		
Weight (g)	PPM	
6.38 E-02	1000000	

Molding Compound			
Item	PPM	Method	
Pb	Not Detected	ICP AES	
Cd	Not Detected	ICP AES	
Hg	Not Detected	ICP AES	
Cr+6	Not Detected	DIN 53314	
PBB	Not Detected	ICP AES	
PBDE	Not Detected	ICP AES	

Die Attach Paste			
Item	PPM	Method	
Pb	<5	ICP AES	
Cd	<5	ICP AES	
Hg	<5	ICP AES	
Cr+6	<5	ICP AES	
PBB	Not Detected		
PBDE	Not Detected		

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Note: The information provided in this declaration are true to the best of ADI's knowledge ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



ADI Proprietary

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Option	Sn/Pb

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SiO2 Filler	85	9.48 E-03	148639	
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Antimony_Sb2O3	0.5	5.58 E-05	874	
Brominated Resin	0.5	5.58 E-05	874	

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Si	0.65	2.38 E-04	3731	
Mg	0.15	5.49 E-05	861	

Internal Leadframe Plating				
Item	% of Plating	Weight (g)	PPM	
Ag	100	5.00 E-04	7838	

External Leadframe Plating				
Item	% of Plating	Weight (g)	PPM	
Sn	85	1.20 E-03	18882	
Pb	15	2.13 E-04	3332	

Bond Wires				
Item	% of Wire	Weight (g)	PPM	
Au	99.99	3.13 E-04	4909	

Chip				
Item	% of Chip	Weight (g)	PPM	
Si	100	1.36 E-02	212859	

Die Attach				
Item	% of Die Attach	Weight (g)	PPM	
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Pb	Not Detected	ICP AES	
Cd	Not Detected	ICP AES	
Hg	Not Detected	ICP AES	
Cr+6	Not Detected	DIN 53314	
PBB	Not Detected	ICP AES	
PBDE	Not Detected	ICP AES	

Die Attach Paste			
Item	PPM	Method	
Pb	<5	ICP AES	
Cd	<5	ICP AES	
Hg	<5	ICP AES	
Cr+6	<5	ICP AES	
PBB	Not Detected		
PBDE	Not Detected		

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